

S/N 10/623,788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Leonard Forbes et al. Examiner: Pamela E. Perkins
Serial No.: 10/623,788 Group Art Unit: 2822
Filed: July 21, 2003 Docket: 1303.109US1
Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
11/318,124 7,429,763	December 23, 2005	1303.095US3	STRAINED SEMICONDUCTOR BY WAFER BONDING WITH MISORIENTATION
11/707,214 7,405,444	February 13, 2007	1303.089US3	MICRO-MECHANICALLY STRAINED SEMICONDUCTOR FILM

These applications have been identified in earlier communications. This communication provides updated information that these applications have now issued.

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 17th day of September, 2008.

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